

CHUCK FOR HOLDING A WORKPIECE

ABSTRACT

5

The invention provides a chuck for holding a workpiece, such as a chip-array semiconductor Chip Scale Packages (CSP) substrate, having a plurality of components such as CSPs to be singulated, and chaff areas of the components. The chuck comprises means to hold the chaff areas when the

10

components are being singulated, that may include a first pressure means to hold the components and a second pressure means to hold the chaff areas.

(Fig. 2)